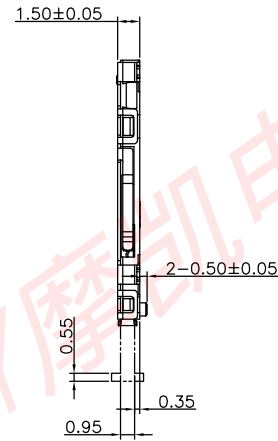
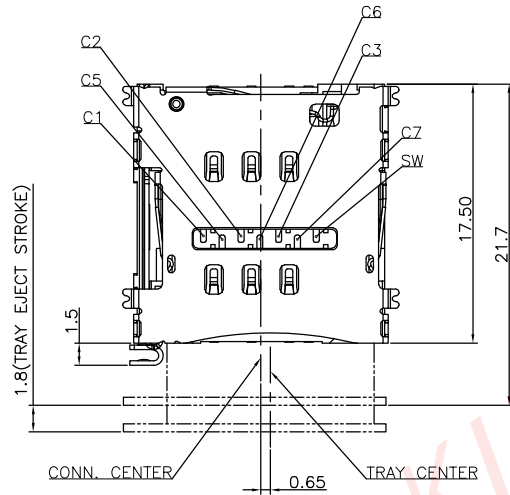
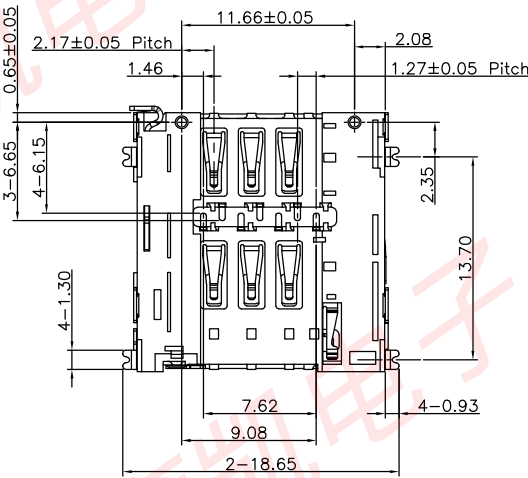
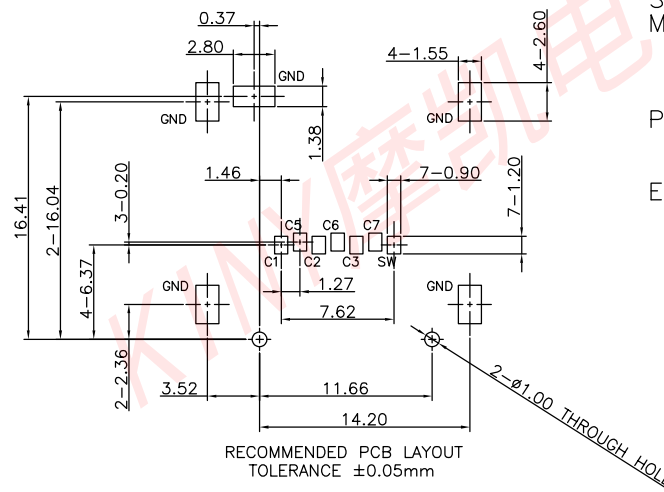
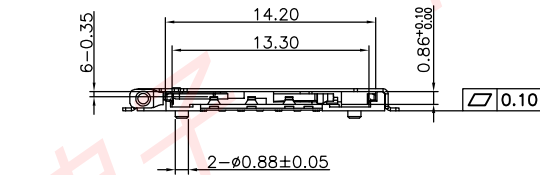
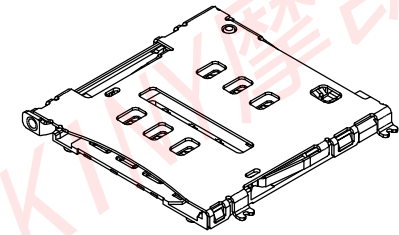


* 所有原料材质, 生产制程, 电镀必须符合H要求



Pin No.	Description
C1	Supply Voltage (Vcc)
C2	Reset (RST)
C3	Clock (CLK)
C5	Ground
C6	Programming Voltage (Vcc)
C7	I/O
SW	Detect Switch
GND	Shielding Ground



Specification :

Material :

Insulator : High Temperature Thermoplastic, UL-94V-0

Contact : Copper Alloy

Shield Shell : Stainless Steel

Plating :

Contact : Plated 50μ" Ni overall, Contact Area 1μ" Au

Shield Shell : Plated 30μ" min. Solderability Ni overall

Electrical :

Current Rating : 0.5A

Voltage Rating : 30V AC/DC

Ambient Temperature Range : -20 C~+85 C

Storage Temperature Range : -50 C~+100 C

Ambient Humidity Range : 95% R.H. Max.

Contact Resistance : 100m Ω Max.

Insulation Resistance : 1000M Ω Min. /500V DC

Mating Cycles : 3000Min Insertions

KINY

东莞市摩凯电子有限公司

DIMENSIONS INIT: mm

UNLESS OTHERWISE SPECIFIABLE

DIMENSION TOLERANCE

X.X: ± 0.35

X.XX: ± 0.20

X.XXX: ± 0.10

ANGULAR: ± 2'

PRODUCT NAME :
Micro SIM H1.50

PRODUCT NO. :
MS150-T1130-01

DRAWING NO. :
D-MS150-T1130-01

DRAWING:
Jack

CHECK:
Alex

APPROVED:
Alex

DATE:
2019.06.01

DATE:
2019.06.01

DATE:
2019.06.01

SCALE:
1:1

DWG ID:
C D

REV.:
A

PAGE:
1 of 1

REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
A	---	NEW RELEASE	Jack	2019.06.01